

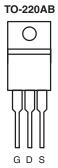
N-Channel 100-V (D-S) 175 °C MOSFET

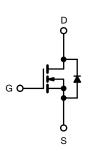
PRODUCT SUMMARY					
V _{DS} (V)	100				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0. 009				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0. 020				
I _D (A)	100				
Configuration	Single				

FEATURES

- TrenchFET® Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter			Limit	Unit	
Drain-Source Voltage			100	V	
Gate-Source Voltage			± 20	V	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	l _n	100		
	T _C = 125 °C	I _D	75 ^a	^	
Pulsed Drain Current	I_{DM}	300	Α		
Avalanche Current	L = 0.1 mH	I _{AS}	75		
Single Pulse Avalanche Energy ^b	L = 0.1 IIII1	E _{AS}	280	mJ	
Maximum Power Dissipation ^b	T_C = 25 °C (TO-220AB and TO-263)	PD	250 ^c	W	
	T _A = 25 °C (TO-263) ^d	ט י	3.75] **	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) ^d	R _{thJA}	40	°C/W		
Junction-to-Ambient	Free Air (TO-220AB)	□thJA	62.5			
Junction-to-Case		R _{thJC}	0.6			

Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS} $V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$ 100				V		
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$			4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.009		Ω	
		$V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		0.020			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.023			
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.030			
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b			•				
Input Capacitance	C _{iss}			4700		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		665			
Reverse Transfer Capacitance	C _{rss}			265			
Total Gate Charge ^c	Q_g			105	160		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 85 \text{ A}$		17		nC	
Gate-Drain Charge ^c	Q_{gd}	1		23			
Turn-On Delay Time ^c	t _{d(on)}			12	25		
Rise Time ^c	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		90	135		
Turn-Off DelayTime ^c	t _{d(off)}	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85	ns	
Fall Time ^c	t _f	1		130	195	1	
Source-Drain Diode Ratings and Char	racteristics T _C	= 25 °C ^b					
Continuous Current	Is				85		
Pulsed Current	I _{SM}				240	Α	
Forward Voltage ^a	V _{SD}	I _F = 85 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			85	140	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, dI/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q _{rr}	1		0.17	0.35	μС	

Notes:

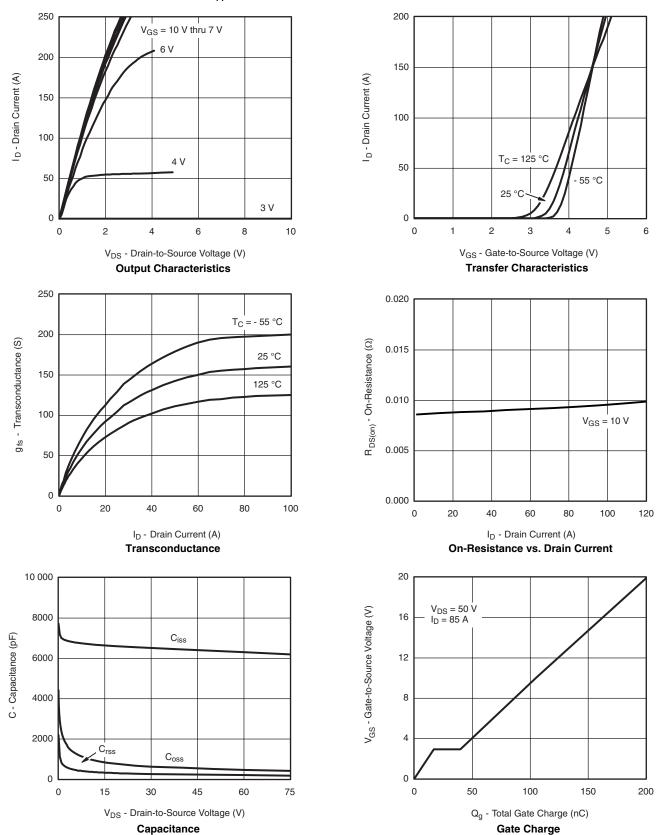
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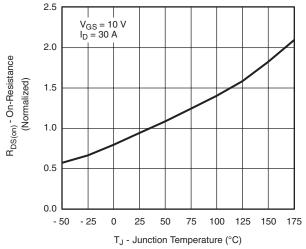
TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



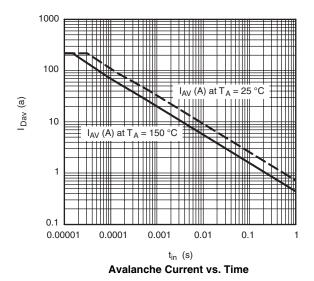
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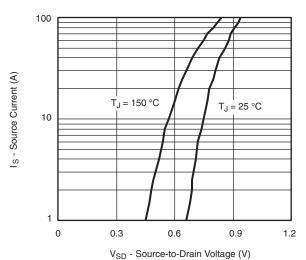


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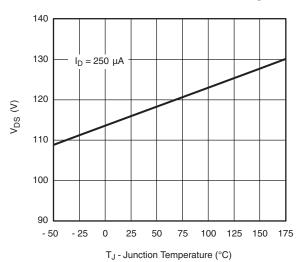


On-Resistance vs. Junction Temperature





Source-Drain Diode Forward Voltage

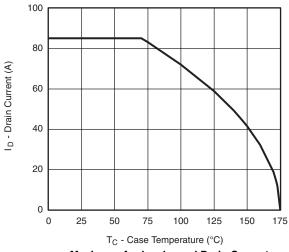


T_J - Drain-Source Breakdown vs. Junction-Temperature

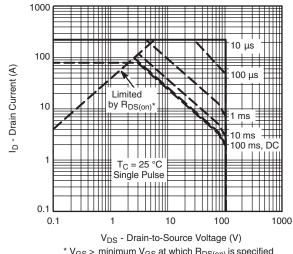
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THERMAL RATINGS

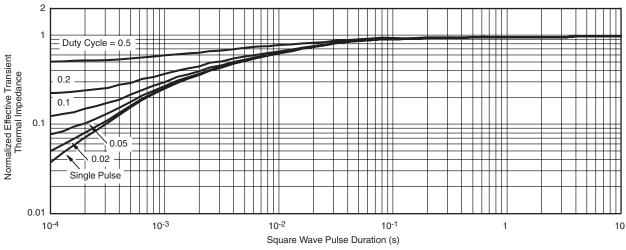






* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area



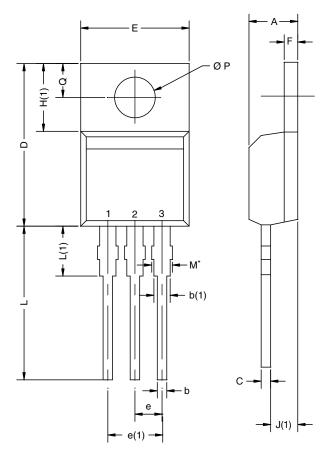
Normalized Thermal Transient Impedance, Junction-to-Case

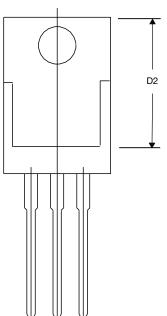
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TO-220AB





	MILLIN	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

Note

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM

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